S11MD4V/S11MD4T

■ Features

- 1. Pin No. 5 completely molded for external noise resistance (S11MD4T)
- 2. Dual-in-line package type (S11MD4V)
- 3. Built-in zero-cross circuit
- 4. High repetitive peak OFF-state voltage $(V_{DRM}: MIN. 400V)$
- 5. Isolation voltage between input and output $V_{iso} : 5 000 V_{rms}$ (S11MD4V/S11MD4T)
- 6. Recognized by UL, file No.E64380
- * S11MD4V and S11MD4T are for 100V lines.

■ Applications

1. For triggering medium/high power triacs

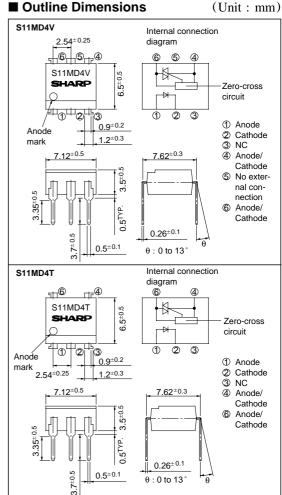
■ Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

Parameter		Symbol	Rating S11MD4V/S11MD4T	Unit			
Input	Forward current	I_F	50	mA			
	Reverse voltage	VR	6	V			
Output	RMS ON-state current	I_T	0.1	A _{rms}			
	*1Peak one cycle surge current	Isurge	1.2	A			
	Repetitive peak OFF-state voltage	V _{DRM}	400	V			
*2 Isolation voltage		V_{iso}	5 000	V_{rms}			
Operating temperature		Topr	- 30 to +100	°C			
Storage temperature		T _{stg}	-55 to +125	°C			
*3 Soldering temperature		T _{sol}	260	°C			

Phototriac Coupler with Built-in Zero-cross Circuit

■ Outline Dimensions



^{*1 50}Hz sine wave

^{*2 40} to 60% RH, AC for 1 minute, f = 60Hz

^{*3} For 10 seconds

■ Electro-optical Characteristics

 $(Ta = 25^{\circ}C)$

Parameter		Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Input	Forward voltage	$V_{\rm F}$	$I_F = 20mA$	-	1.2	1.4	V
	Reverse current	I_R	$V_R = 3V$	-	-	10-5	A
Output	Repetitive peak OFF-state current	I_{DRM}	$V_{DRM} = Rated$	-	-	10-6	A
	ON-state voltage	V _T	$I_T = 0.1A$	-	1.7	2.5	V
	Holding current	I_{H}	$V_D = 6V$	0.1	1.0	3.5	mA
	Critical rate of rise of OFF-state voltage	dV/dt	$V_{DRM} = 1/\sqrt{2} \cdot Rated$	100	-	-	$V/\mu \ s$
	Zero-cross voltage	Vox	Resistance load, I _F = 15mA	-	-	35	V
Transfer characteristics	Minimum trigger current	I_{FT}	$V_D = 6V. R_L = 100\Omega$	-	-	10	mA
	Isolation resistance	Riso	DC500V, 40 to 60% RH	5 x 10 ¹⁰	1011	-	Ω
	Turn-on time	t _{on}	$V_D = 6V, R_L = 100\Omega, I_F = 20mA$	-	20	50	μs

Fig. 1 RMS ON-state Current vs. Ambient Temperature

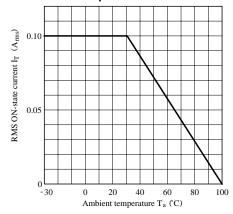


Fig. 3 Forward Current vs. Forward Voltage

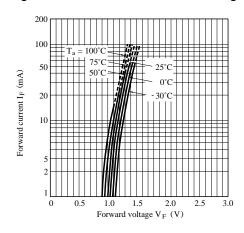


Fig. 2 Forward Current vs. Ambient Temperature

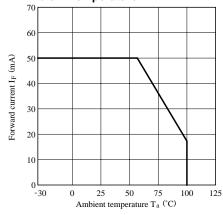


Fig. 4 Minimum Trigger Current vs. Ambient Temperature

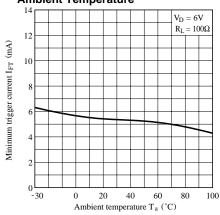


Fig. 5 Relative Repetitive Peak OFF-state Voltage vs. Ambient Temperature

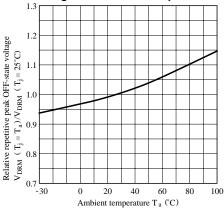


Fig. 7 Holding Current vs.

Ambient Temperature

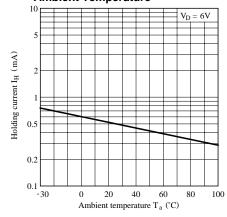


Fig. 9 Repetitive Peak OFF-state Current vs. Ambient Temperature

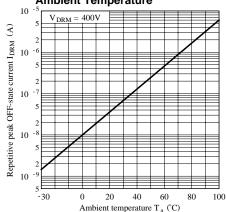


Fig. 6 ON-state Voltage vs.
Ambient Temperature

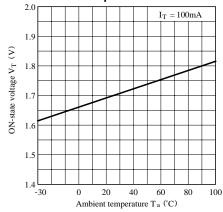


Fig. 8 Repetitive Peak OFF-state Current vs. OFF-state Voltage

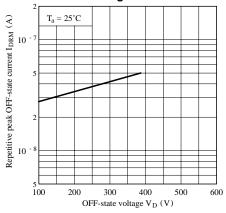


Fig.10 Zero-cross Voltage vs.
Ambient Temperature

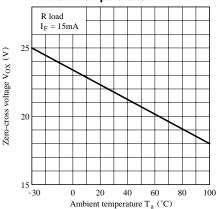
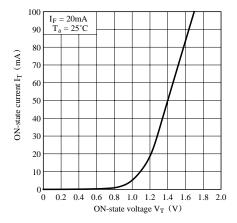


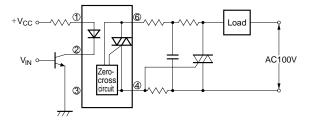


Fig.11 ON-state Current vs. ON-state Voltage



■ Basic Operation Circuit

Medium/High Power Triac Drive Circuit



Note) Please use on condition of the triac for power triggers.

• Please refer to the chapter "Precautions for Use."

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